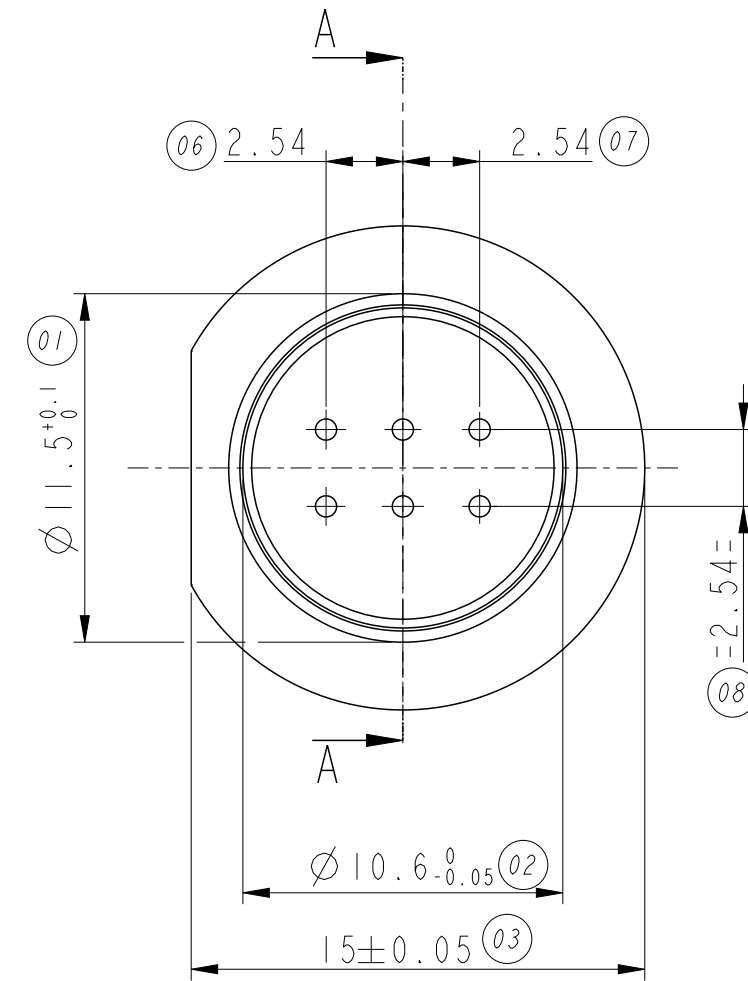
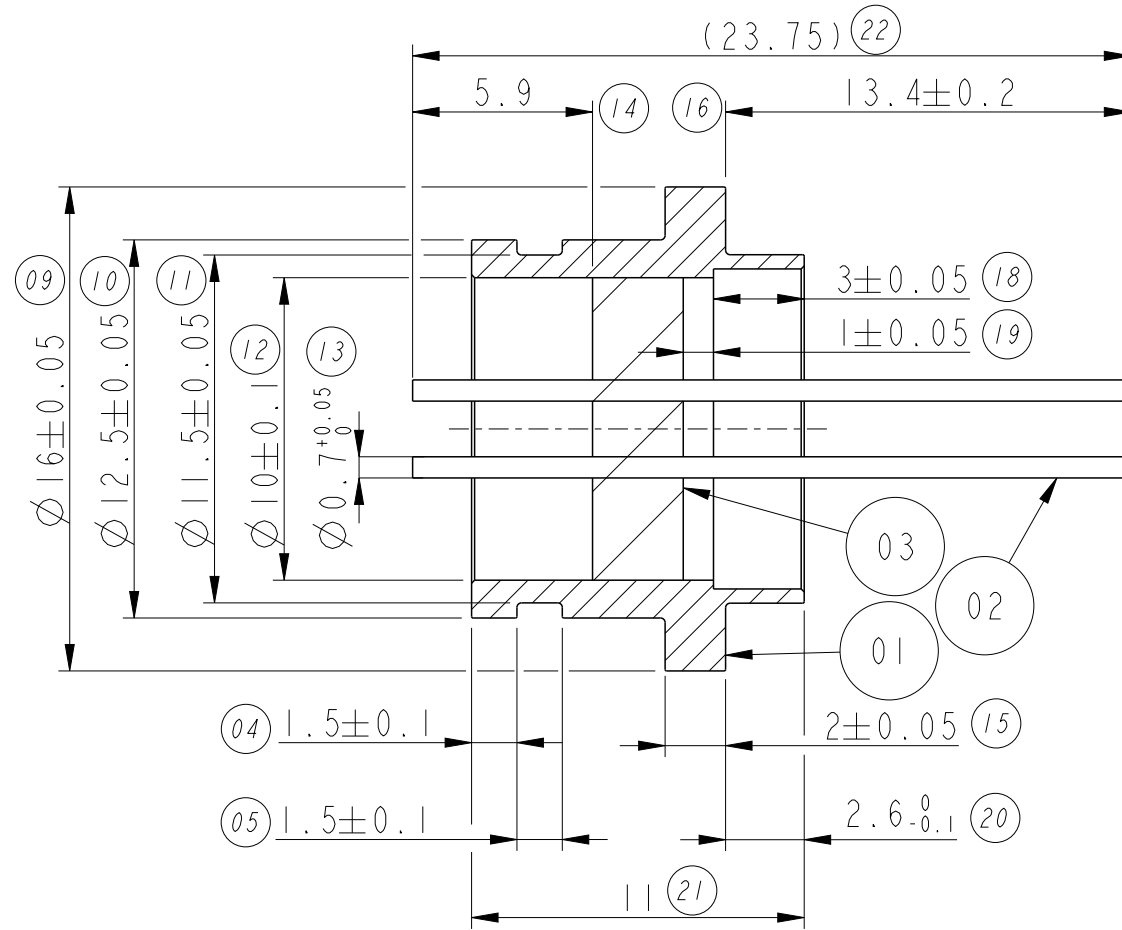
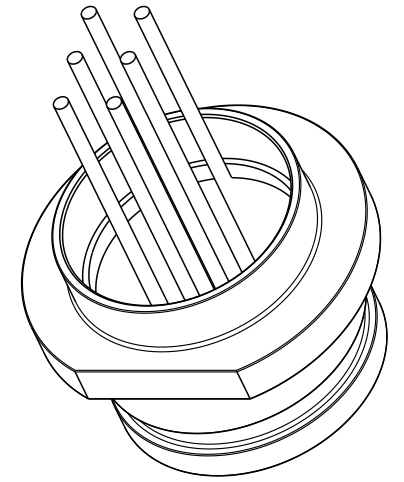


PLATING:

Body & Pins - Base Electrolytic Ni 7-10 µm,
 Followed by Electroless Ni 4-7 µm,
 then gold(Au) 0.07 µm avg (0.25 µm Max)
 APA: 1200mm²

NOTES:

- This product meets european union directives and other country regulations as described in GS-47-0004 (RoHS & REACH Compliant)



SECTION A-A
 SCALE 4:1

AFCI P/N: 10144569-002LF

SPECIFICATIONS:

- HELIUM LEAKAGE RATE : $1 \times 10^{(-6)}$ Pa.m⁽³⁾/s
- INSULATION RESISTANCE : > 1000 MΩ (500 VDC)
- DIELECTRIC WITHSTANDING VOLTAGE - 1000 Vrms (cts to cts & cts to shell)
- CONTACT RATING : 1A
- CONTACT RESISTANCE : <20 mΩ

3	INSERT	1	GLASS PREFORM
2	CONTACT PIN	6	Ni10 48-52
1	SHELL/FERRULE	1	LEADED MS
SN	DESCRIPTION	QTY	MATERIAL

spec ref	-	dr	Rameshan, Biru	2022/02/28	projection	MM	size	A3	scale	4:1
tolerance std	ISO 406 ISO 1101	eng	Rameshan, Biru	2022/03/01			ecn no	-	rel level	Released
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	product family						
surface	1.6	appr	Kuriakose, San	2022/03/01	6 PIN HERMETIC CONNECTOR ASSEMBLY		dwg no	10144569c	rev	A
ISO 1302	linear	0.X	±0.1	amphenol-icc.com		cat. no.	-	Product - Customer Drw	sheet 1 of 1	
	angular	0.XX	±0.05							
		0.XXX	±-							
		0°	±0.5°							